



—Thermal conductive & insulation—  
Adhesive sheet **“EA series”**

Example of use

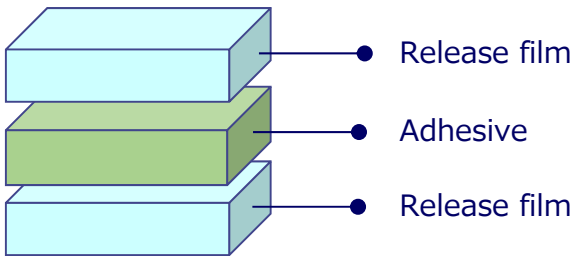
- Power module
- Substrate for LED
- Infrastructure & Substrate for photovoltaics



Characteristics

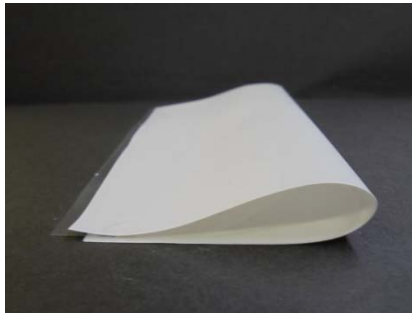
- Semi-cured adhesive sheet having thermal conductivity and insulation resistance.
- Thickness lineup from 10 to 200 $\mu$ m. (Thickness lineup defers depending on the thermal conductivity level of product)

Product structure



Customization available per customers request.

■ Appearance



※Flexibility is dependent on product models.

Product Properties

Thin type  
(1W-20 $\mu$ m)

Product model: **EAF 20PT**

Thin product with adhesive thickness of 20 $\mu$ m. With consideration of thermal resistance, thermal conductivity is equivalent to 10W on 100 $\mu$ m.

Standard  
(3W-100 $\mu$ m)

Product model: **EAJ 100PT**

The product of 100 $\mu$ m adhesive, having good balance between thermal conductivity, adhesion, and insulation resistance.

High thermal conductivity  
(15W-150 $\mu$ m)

Product model: **EAM 150PT**

The product with high thermal conductivity. High performance in thermal conductivity and insulation resistance.

※Recommended forming condition: pressing at 180 $^{\circ}$ C (Holding 180 $^{\circ}$ C for 60min with 3 to 20MPa)